IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. If SINDUSTRIES® international and Pan	C, Bannockb	urn, Illinois. A	all rights reserved un	nder both	This docume level parts, t	ent is a declar the declaration	ration on encor	of the substances mpasses all lowe	within th r level ma	e manufactur aterials for w	rer listed it hich the m	em. Note: i	if the item is an as r has engineering	sembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information						
Supplie	r Information															
Company name* Company unique I				ique ID	ie ID Ur			Unique ID Authority					Response Date*			
onsemi												2024-05-03				
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	Date Version Manufacturing Site		uring Site	Weight*		UOM	Unit Type		
		1N5920BRLG ZI		ZEN SUR30 REG 3W 6.2V			2024-05-03			CNP		3	861.01	mg	Each	
Manufa	cturing Proccess Informat	ion										1				
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-02		-STD-020 MSI	_ Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperat	ure Numb	per of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy NA		IA.		0 C		30 seco		secon	ds 3					
omments	3															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed							
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the provided certification in	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.67	mg	Supplier	Silicon (Si)	7440-21-3		2.67	mg
Die Attach Solder	12.67	mg	Supplier	Silver (Ag)	7440-22-4		0.3168	mg
			A	Lead (Pb)	7439-92-1	7a	11.7198	mg
			Supplier	Tin (Sn)	7440-31-5		0.6335	mg
Lead Frame	198.45	mg	В	Nickel (Ni)	7440-02-0		2.183	mg
			Supplier	Copper (Cu)	7440-50-8		196.267	mg
Mold Compound-Black	139.28			Metal Hydroxide	proprietary data		6.964	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3928	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		104.46	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		13.928	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		12.5352	mg
Plating	7.94	mg	Supplier	Tin (Sn)	7440-31-5		7.94	mg